

Notice of References Cited	Application/Control No. 10/721,260	Applicant(s)/Patent Under Reexamination SAKATA, TOYOKAZU	
	Examiner Patricia A. George	Art Unit 1765	Page 1 of 1

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*	B	US-4,931,144	06-1990	Brighton, Jeffrey E.	174/262
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NON-PATENT DOCUMENTS

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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.